

## Interface Engineering and Oxygen Vacancy Derived from Plasma-treated Cu<sub>2</sub>O Synergistically Enhancing Electrocatalytic CO<sub>2</sub>-to-C<sub>2+</sub> Conversion

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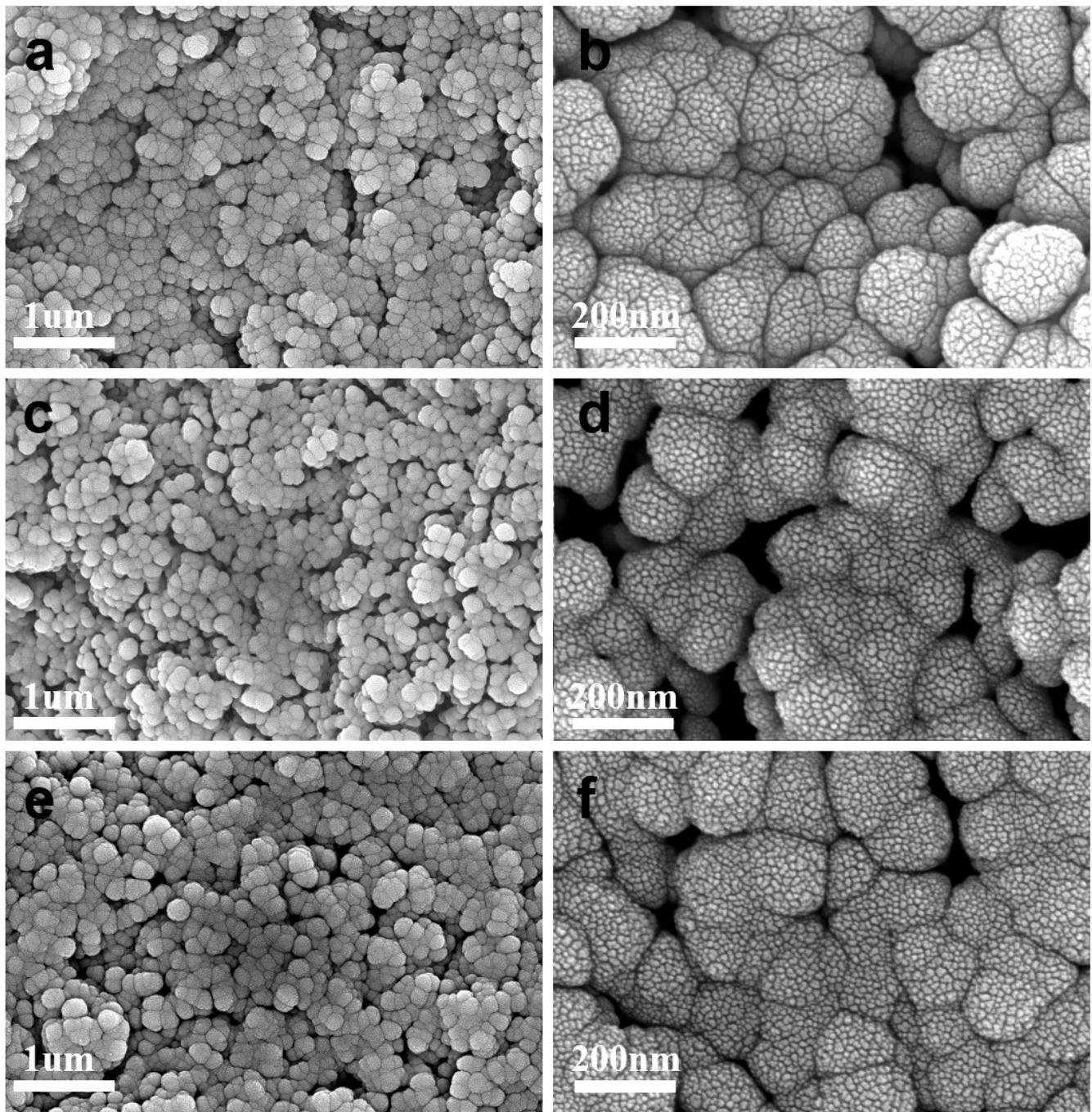
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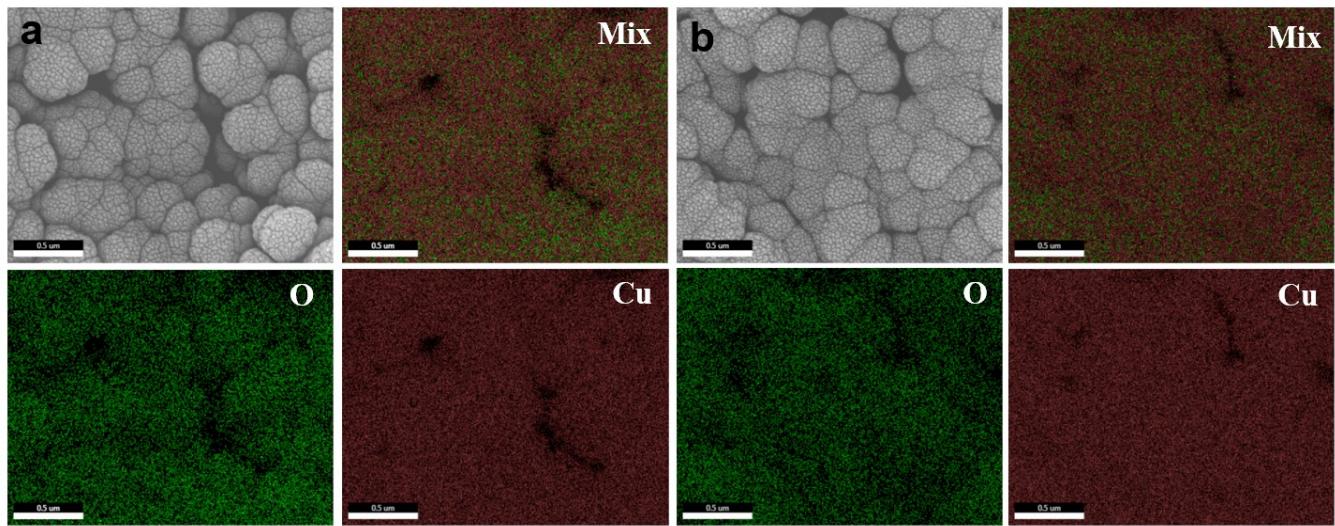
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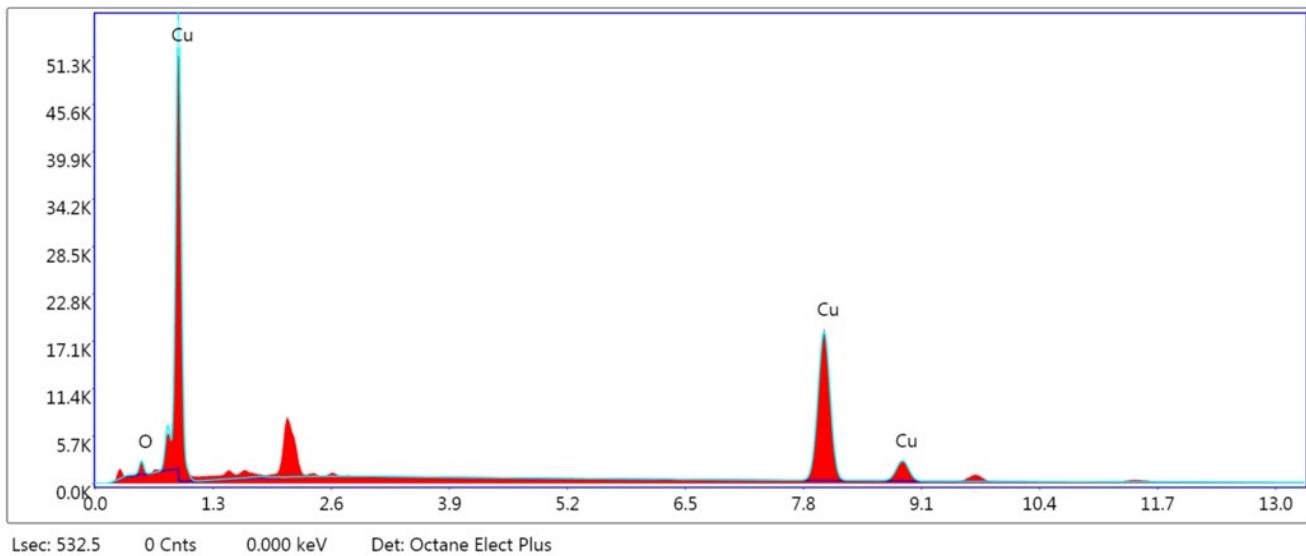
This supplementary information includes: Figure S1 to S12 and Table S1-3.



**Figure S1.** (a-f) SEM images of Cu<sub>2</sub>O (a-b), Cu<sub>2</sub>O-Ar/H<sub>2</sub> (c-d) and Cu<sub>2</sub>O-Ar/O<sub>2</sub> (e-f).

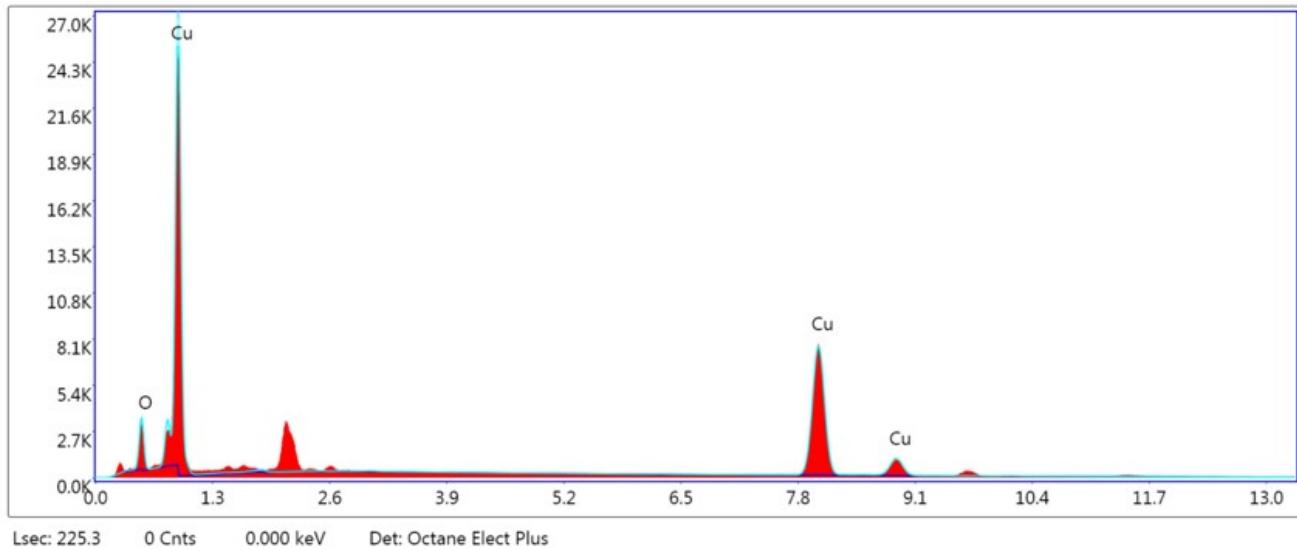


**Figure S2.** (a-b) SEM-EDS elemental mapping images of Cu<sub>2</sub>O (a) and Cu<sub>2</sub>O-Ar/O<sub>2</sub> (b).



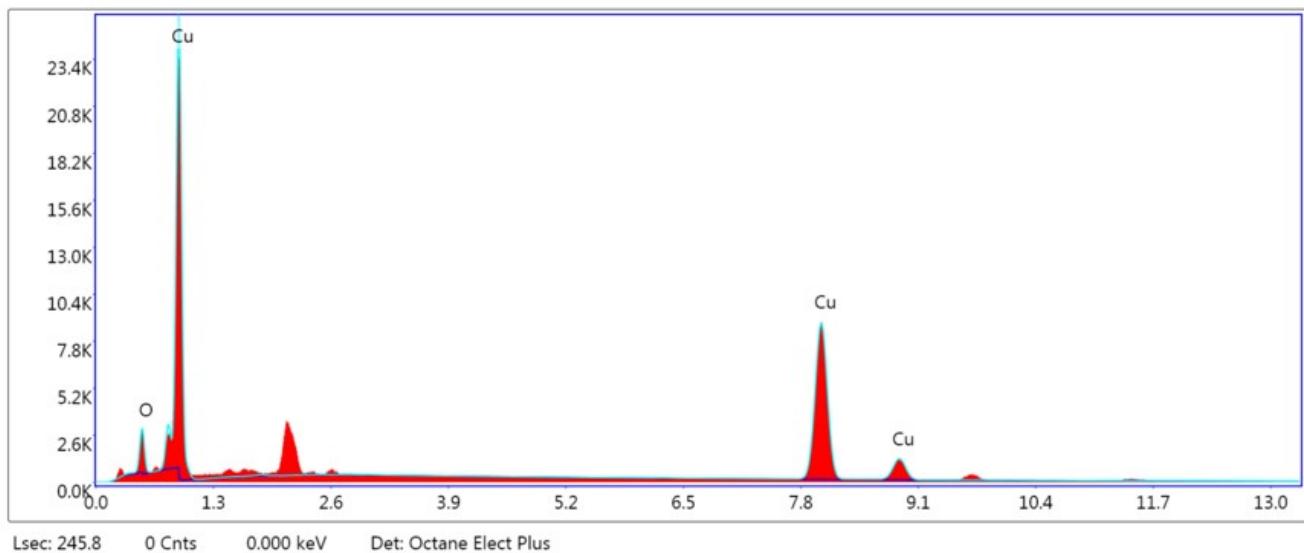
Element	Weight %	Atomic %	Net Int.	Error %	Kratio
O K	2.50	9.24	38.90	9.60	0.0105
Cu K	97.50	90.76	1102.10	1.75	0.9670

**Figure S3.** (a) Element content distribution of Cu<sub>2</sub>O-Ar/H<sub>2</sub>.



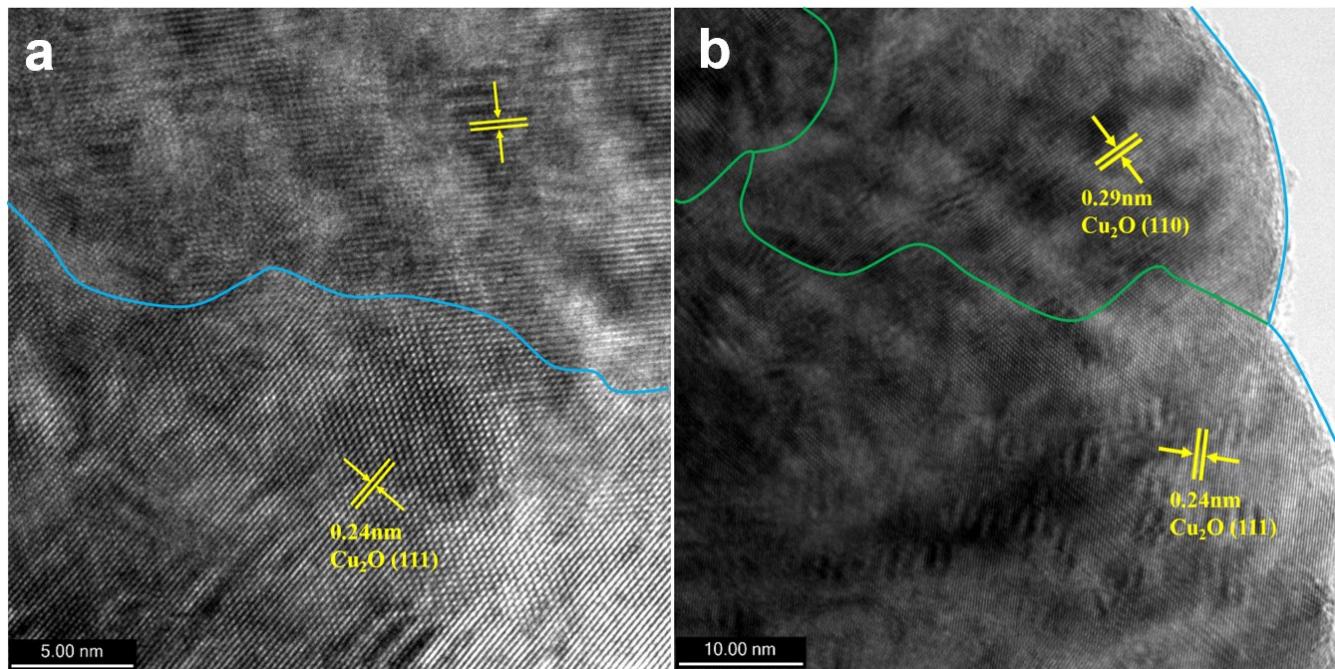
Element	Weight %	Atomic %	Net Int.	Error %	Kratio
O K	14.56	40.37	158.20	8.85	0.0646
Cu K	85.44	59.63	615.00	2.28	0.8151

**Figure S4.** (a) Element content distribution of  $\text{Cu}_2\text{O}$ .

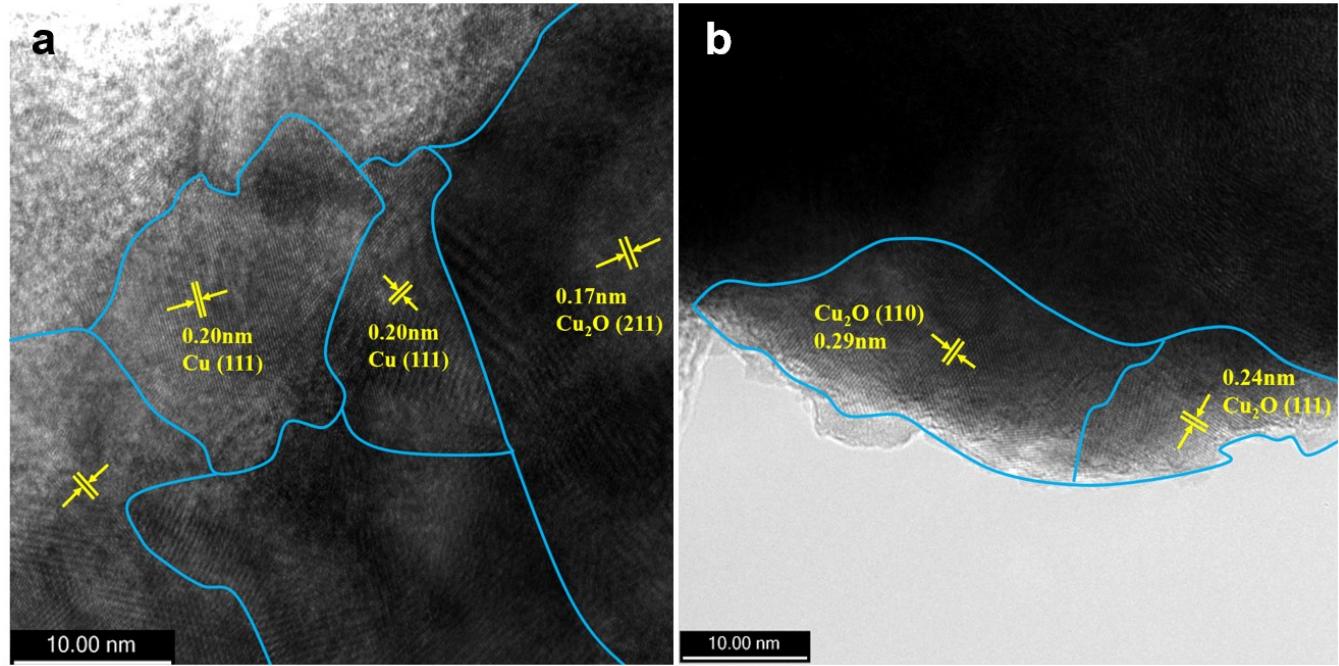


Element	Weight %	Atomic %	Net Int.	Error %	Kratio
<b>O K</b>	12.07	35.28	123.40	9.15	0.0529
<b>Cu K</b>	87.93	64.72	607.10	2.32	0.8456

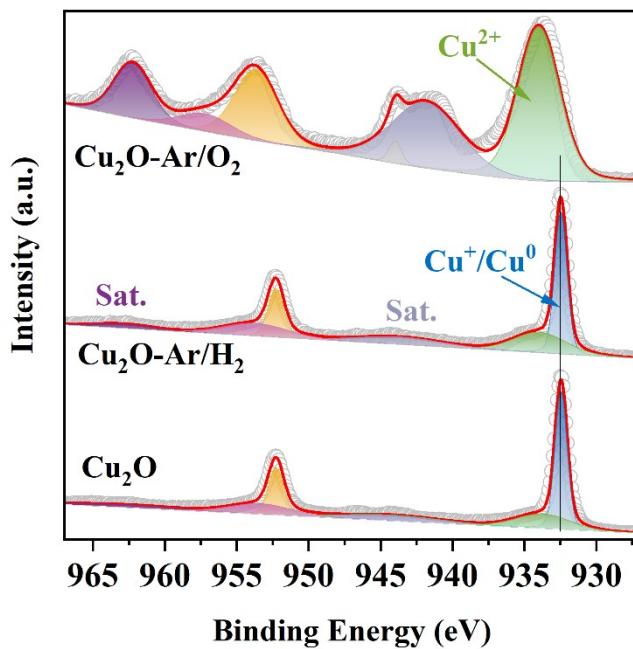
**Figure S5.** (a) Element content distribution of Cu<sub>2</sub>O-Ar/O<sub>2</sub>.



**Figure S6.** (a-b) HRTEM images of  $\text{Cu}_2\text{O}$ .



**Figure S7.** (a-b) HRTEM images of Cu<sub>2</sub>O-Ar/H<sub>2</sub> (a) and Cu<sub>2</sub>O-Ar/O<sub>2</sub> (b).

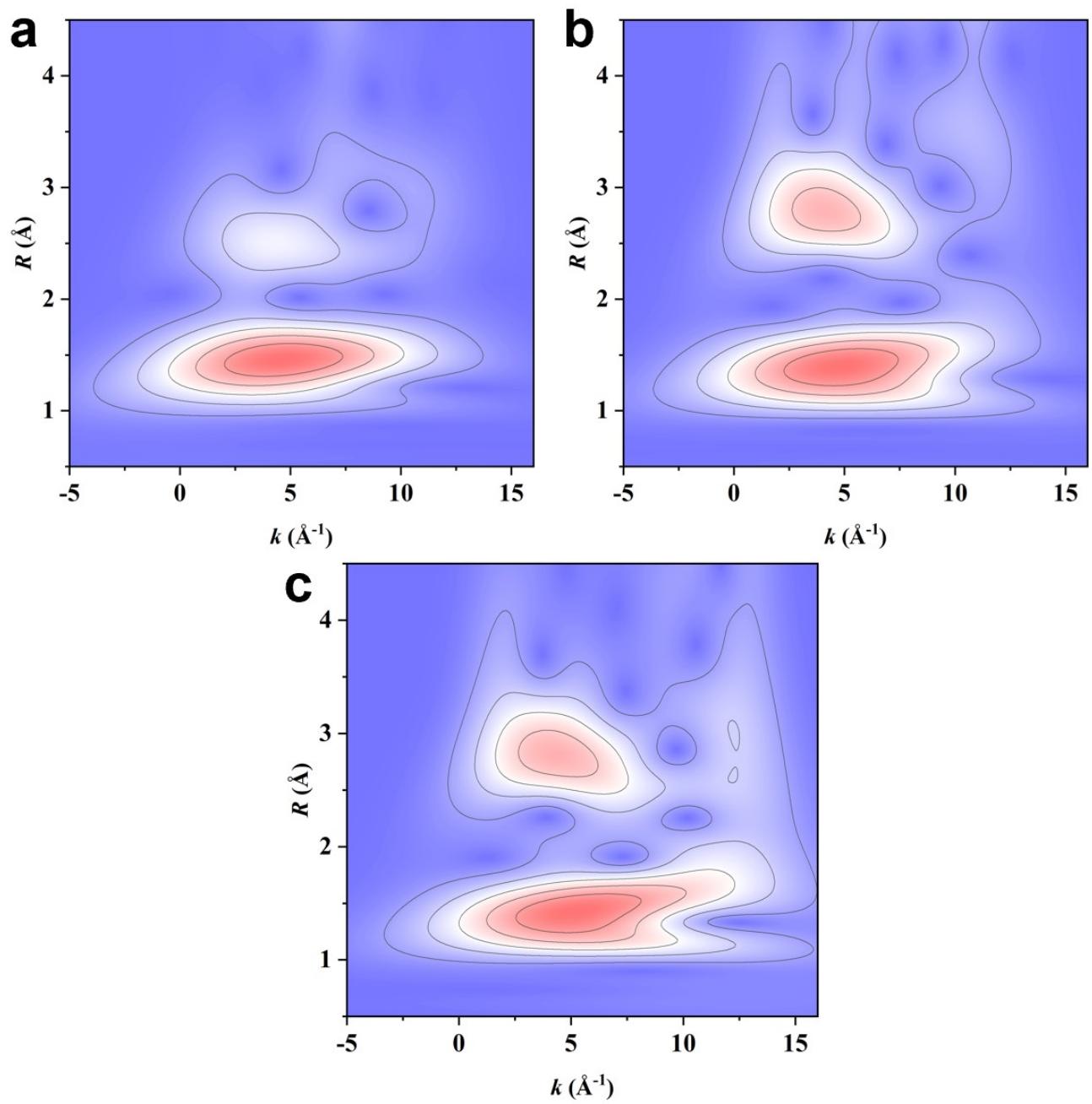


**Figure S8.** Cu 2p XPS spectra of as-prepared catalysts.

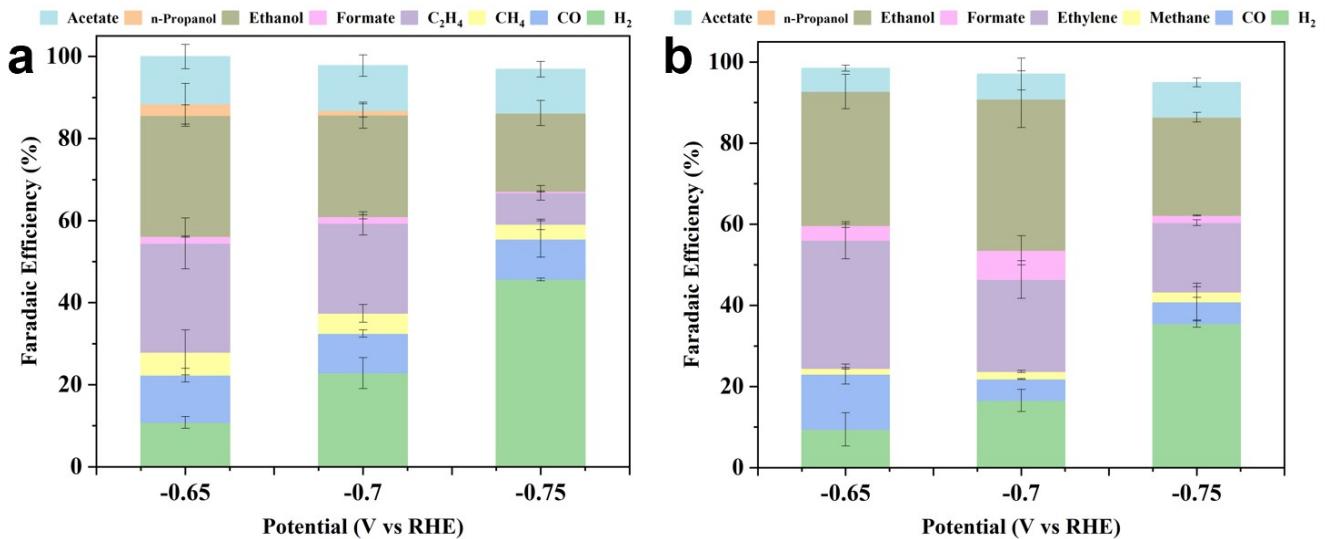
**Table S1.** Fitted EXAFS parameters at Cu K-edge for Cu<sub>2</sub>O, Cu<sub>2</sub>O-Ar/H<sub>2</sub>, Cu<sub>2</sub>O-Ar/O<sub>2</sub>, Cu<sub>2</sub>O, and CuO reference.

Sample	Path	R-factor	N	R (Å)	$\sigma^2$ (Å <sup>2</sup> )
<b>CuO reference</b>	Cu-O	5.1	4	1.94±0.008	3.8±1.0
<b>Cu<sub>2</sub>O reference</b>	Cu-O	0.0244	2	1.85±0.01	0.003
	Cu-Cu		12	3.03±0.03	0.032
<b>Cu<sub>2</sub>O</b>	Cu-O	0.016	1.90	1.84±0.004	0.002
	Cu-Cu		13.1	3.01±0.006	0.032
<b>Cu<sub>2</sub>O-Ar/H<sub>2</sub></b>	Cu-O	0.01	1.77	1.79±0.06	0.0019
	Cu-Cu		12.0	2.94±0.06	0.019
<b>Cu<sub>2</sub>O-Ar/O<sub>2</sub></b>	Cu-O	0.015	1.65	1.84±0.05	0.001
	Cu-Cu		0.24	2.89±0.03	0.004

N: coordination number;  $\sigma^2$ : mean-square disorder; R-factor: goodness of EXFAS fitting.

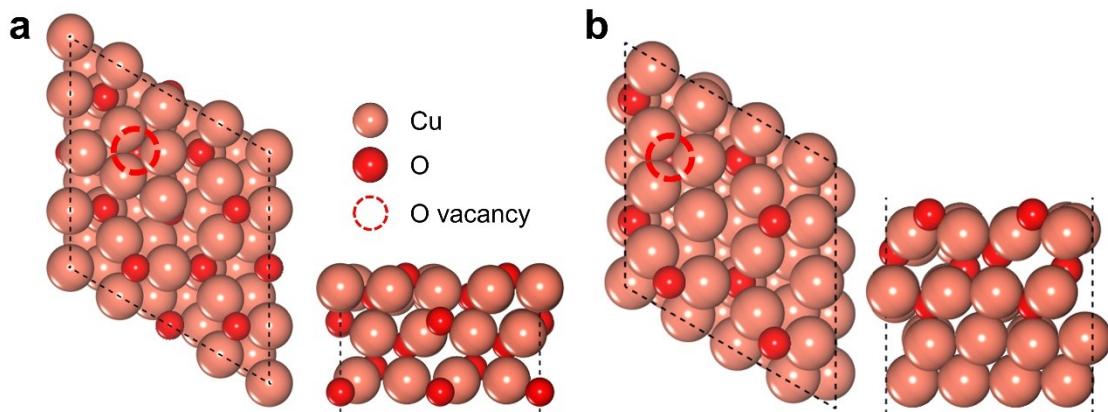


**Figure S9.** (a-c) Wavelet transforms for the  $k^3$ -weighted EXAFS signals of CuO reference (a), original Cu<sub>2</sub>O (b), and Cu<sub>2</sub>O-Ar/O<sub>2</sub> (c).

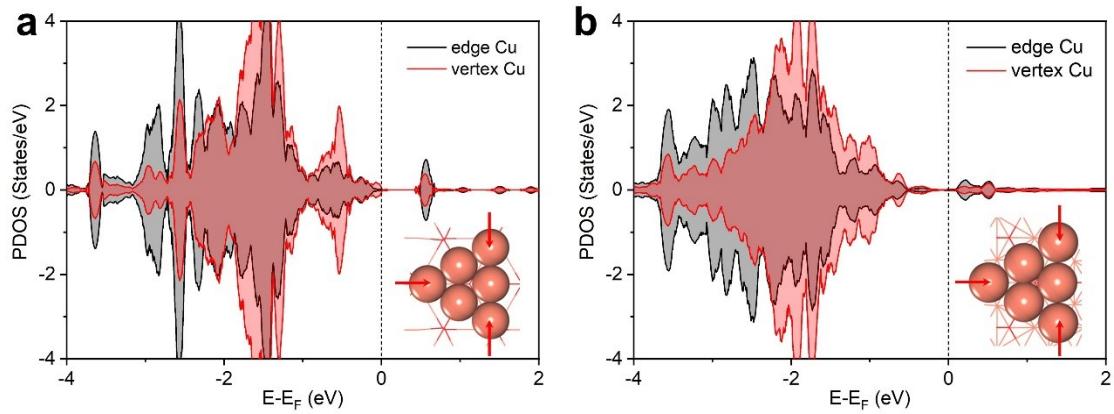


**Table S2.** The summary of ECR performances for C<sub>2+</sub> products over various plasma-treated electrocatalysts.

Catalysts	Electrolytes	Reactor	C <sub>2+</sub> FE (%)	Ref.
Cu <sub>2</sub> O-Ar/H <sub>2</sub>	1M KOH	Flow cell	81.2	This work
F-Cu	1M KOH	Flow cell	81.6	[1]
Cu <sub>2</sub> O(CO)	1M KOH	Flow cell	77.4	[2]
Cu nanocube	0.1M KHCO <sub>3</sub>	H cell	73	[3]
ON-CuO	0.1M KHCO <sub>3</sub>	H cell	77	[4]
OD-Cu	0.1M KHCO <sub>3</sub>	H cell	60	[5]
dendritic Cu	0.1M KHCO <sub>3</sub>	H cell	45	[6]
Ar <sub>10min</sub> -plasma Cu	0.1 M CsHCO <sub>3</sub>	H cell	57.2	[7]
O <sub>2,10min</sub> -plasma Cu	0.1 M CsHCO <sub>3</sub>	H cell	58.8	[7]



**Figure S11.** Top and side views of (a)  $\text{Cu}_2\text{O}$  and (b)  $\text{Cu}_2\text{O}-\text{Ar}/\text{H}_2$ .



**Figure S12.** PDOS of vertex and edge Cu atoms of (a) Cu<sub>2</sub>O and (b) Cu<sub>2</sub>O-Ar/H<sub>2</sub>, where red arrows denote vertex atoms.

**Table S3.** Energies ( $E$ ) and reaction energies ( $\Delta E$ ) of  $^*\text{CO}$  and  $^*\text{CHO}$  on  $\text{Cu}_2\text{O}-\text{Ar}/\text{H}_2$  and  $\text{Cu}_2\text{O}$  with ( $E_{\text{sol}}$ ) and without ( $E_0$ ) the solvation effect.

	$\text{Cu}_2\text{O}-\text{Ar}/\text{H}_2$		$\text{Cu}_2\text{O}$	
	$E_0$ (eV)	$E_{\text{sol}}$ (eV)	$E_0$ (eV)	$E_{\text{sol}}$ (eV)
$E_{^*\text{CO}}$	-366.06	-336.60	-343.20	-343.81
$E_{^*\text{CHO}}$	-338.80	-339.37	-346.14	-346.78
$\Delta E_{\text{CHO-CO}}$	0.65	0.61	0.44	0.42

## **Reference:**

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